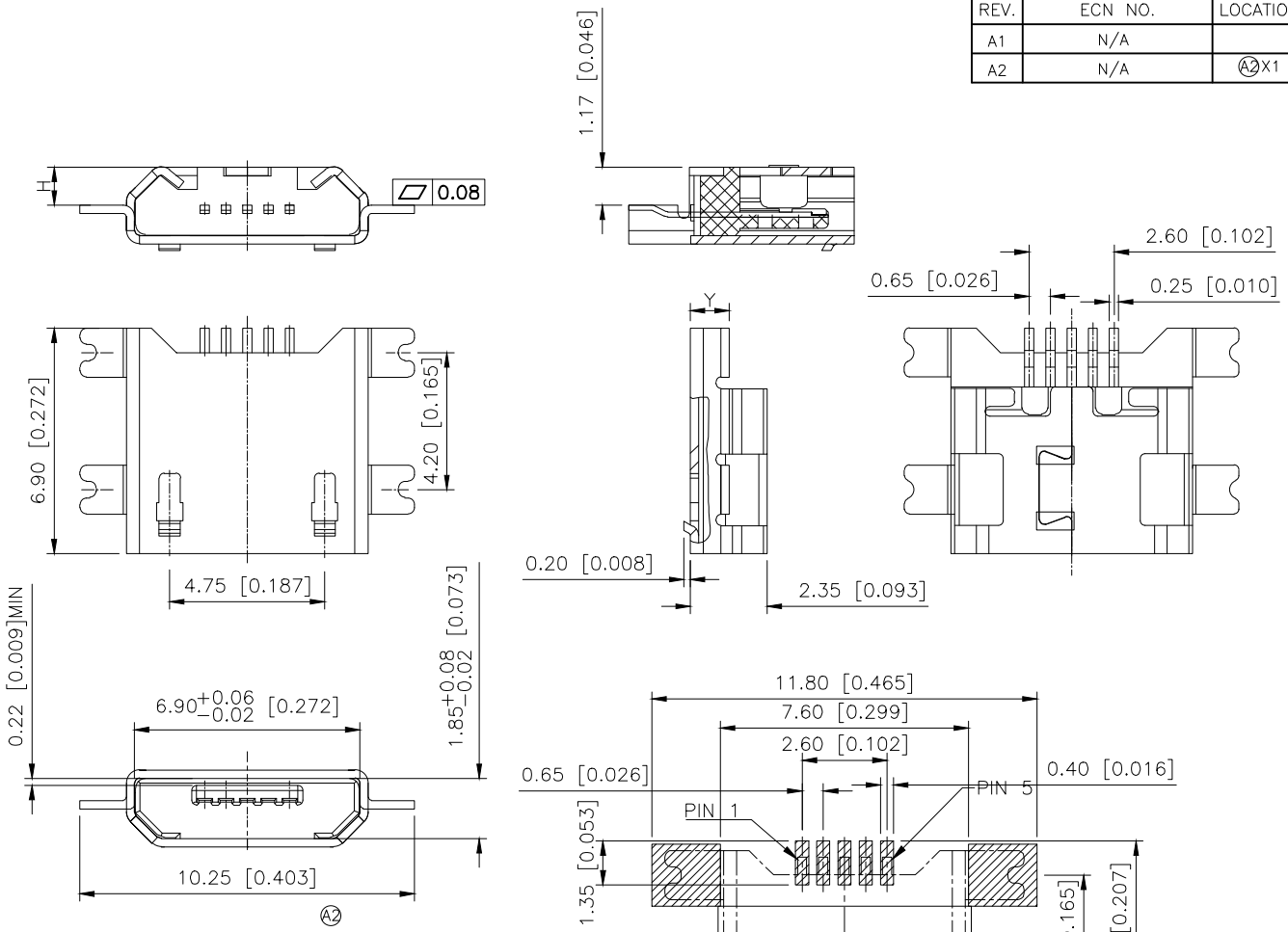
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A1	N/A		图面升级整理图面	2025.03.04	阿树
A2	N/A	A2 X1	产品尺寸变更	2025.10.10	阿树



RECOMMANDED PCB LAYOUT

Note:
1.Material:
1.1 Housing: High temperature thermoplastic with g.f, UL94V-0
1.2 Contact:copper alloy,t=0.15mm
1.3 Shell:copper alloy,t=0.25mm
2.Specification:
2.1 Current rating:1A Max
2.2 Dielectric withstanding voltage:100V(ac) for 1 min.
2.3 Contact resistance:30 MΩ Max.
2.4 Insulation resistance:100 MΩ Min。
2.5 Total mating force:3.57 Kgf Max.
2.6 Total unmating force:0.80 Kgf Min.
2.7 Temperature range:-30℃~80℃

U253-05XX-4BH87-FX

1:AU 1U''
6:AU 30U''
T:TIN
N:NICKEL

1:H1.2 2:H1.17 3: H0.7
S:Scrolls F:Flat

X	1	2	3
H	1.2	1.17	0.7
Y	1.15	1.18	1.65

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAuCES	

XKB Connection 星创

DESIGN	阿树	VIEW:	MODEL TYPE: MICRO USB
CHECKED		UNIT: mm/in	PART NO.: U253-05XX-4BH87-FX
APPROVED		SIZE: A4	DWG NO.:

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SCALE	PAGE	REVISION
N/A	1/1	A2